Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-31
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

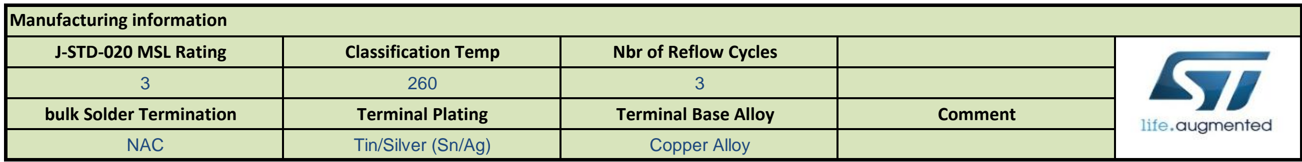
While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F207IEH6TR	S8MR*411XXX1	A	9993	2014-07-31
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	111.59	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin/Silver (Sn/Ag)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10x0.6	176+25	No lead	
Comment	UFBGA 10x10x0.6 176+25 P0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	Description

QueryList : REACH-16th June 2014	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**S8MR*411XXX1**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or Dies	Other inorganic materials	3.987	mg	supplier	die	Silicon (Si)	7440-21-3		2.572	mg	645097	23049
Die or Dies					metallization	Aluminium (Al)	7429-90-5		0.024	mg	6020	215
Die or Dies					metallization	Copper (Cu)	7440-50-8		0.211	mg	52922	1891
Die or Dies					metallization	Tantalum (Ta)	7440-25-7		0.984	mg	246802	8818
Die or Dies					metallization	Cobalt (Co)	7440-48-4		0.001	mg	251	9
Die or Dies					metallization	Titanium (Ti)	7440-32-6		0.002	mg	502	18
Die or Dies					metallization	Tungsten (W)	7440-33-7		0.002	mg	502	18
Die or Dies					passivation	Silicon Nitride (SiN)	68034-42-4		0.054	mg	13544	484
Die or Dies					passivation	Silicon Oxide(SiO2)	7631-86-9		0.137	mg	34362	1228
Encapsulation	Other inorganic materials	59.057	mg	supplier	Mold compound	Silica, vitreous [Fused Silica]	60676-86-0		52.318	mg	885890	468850
Encapsulation					Mold compound	Epoxy resins	N/A		2.344	mg	39690	21006
Encapsulation					Mold compound	Phenolic resins	N/A		1.758	mg	29768	15754
Encapsulation					Mold compound	Carbon black	1333-86-4		0.293	mg	4961	2626
Encapsulation					Mold compound	Metal Hydroxide	N/A		1.758	mg	29768	15754
Encapsulation					Mold compound	Other miscellaneous substances	N/A		0.586	mg	9923	5251
Substrate	Other inorganic materials	40.200	mg	supplier	Core	organic resin	N/A		2.829	mg	70373	25352
Substrate					Core	Silicon dioxide	7631-86-9		1.599	mg	39776	14329
Substrate					Core	Other inorganic filler	N/A		1.599	mg	39776	14329
Substrate					Core	Glass fiber	65997-17-3		6.273	mg	156045	56216
Substrate					Solder mask	Organic resin	N/A		3.705	mg	92164	33202
Substrate					Solder mask	Inorganic filler	N/A		1.995	mg	49627	17878
Substrate					Cu Coil	Copper	7440-50-8		15.100	mg	375622	135319
Substrate					Ni Plating	Nickel	7440-02-0		5.800	mg	144279	51977
Substrate					Au Plating	Gold	7440-57-5		1.300	mg	32338	11650
Die attach	Other inorganic materials	1.444	mg	supplier	Glue	Resins	N/A		0.650	mg	450170	5825
Die attach					Glue	Phenol-formaldehyde polymer	9003-35-4		0.144	mg	99730	1290
Die attach					Glue	Silica	67762-90-7		0.029	mg	20084	260
Die attach					Glue	Proprietary Material	N/A		0.620	mg	429393	5556
Die attach					Glue	Cl	N/A		0.001	mg	623	8
Bonding wire	Other inorganic materials	0.700	mg	supplier	Bonding wire	Gold	7440-57-5		0.700	mg	1000000	6273
Solderball	Other inorganic materials	6.200	mg	supplier	Solder	Tin	7440-31-5		5.983	mg	965000	53617
Solderball					Solder	Silver	7440-22-4		0.217	mg	35000	1945